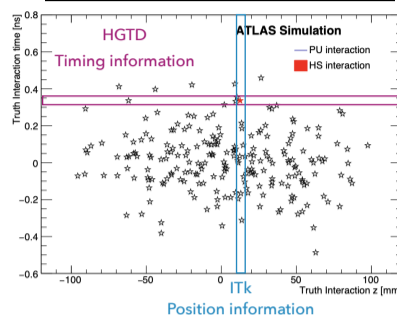
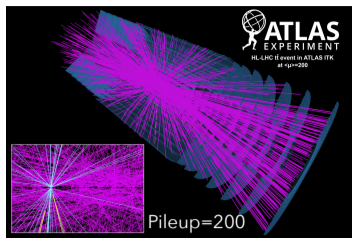


## High-Luminosity LHC

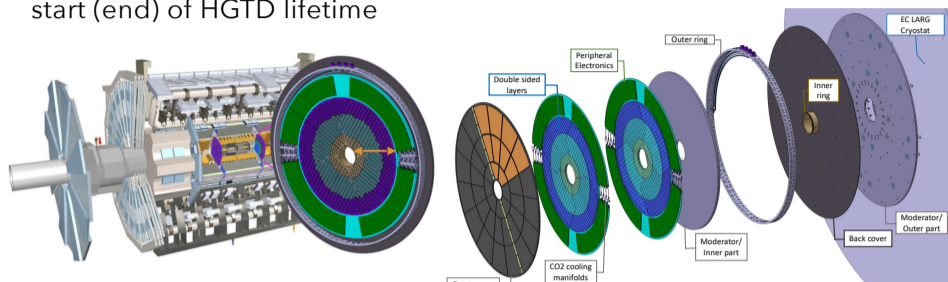
In 2029, the high-luminosity phase of LHC will start

- Instantaneous luminosity up to  $7.5 \times 10^{34} \text{ cm}^{-2} \text{ s}^{-1}$
- Main challenge:** separate collisions very close in space ( $\sim 1.6$  vertices per mm)
- Solution:** HGTD in the forward region of the ATLAS detector providing precise timing information combined to a full silicon tracker (ITk) providing high precision tracking



## HGTD

- Two end-caps located at  $z \pm 3.5 \text{ m}$
- Active area :  $2.4 < |\eta| < 4.0$ ,  $12 < R < 64 \text{ cm}$
- Each is two double-sided layers of modules mounted on cooling disks
- Target time resolution: 30 (50) ps per track, 35 (70) ps per hit at the start (end) of HGTD lifetime

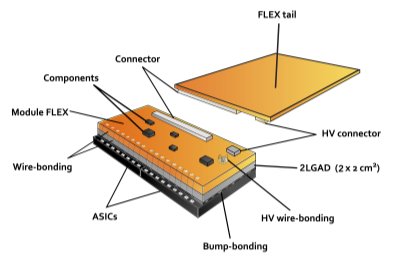


## Module & Sensor

8032 modules: 2 silicon sensors bump-bonded to 2 ALTIROC (ATLAS LGAD Timing Integrated Read Out Chip) ASICs

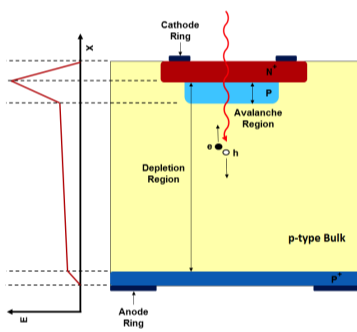
→ **Ongoing:** bench tests of ALTIROC2 modules on flex PCB

→ **Next step:** bench tests of ALTIROC3 modules (radiation hard version of ALTIROC2)



LGAD (Low Gain Avalanche Detector) : standard n-p silicon detector with additional p-type doping layer

- Size: 15x15 pads (1.3x1.3 mm<sup>2</sup> each) and 300 μm thick
- Time resolution: 30 (50) ps per track at the start (end) of HL-LHC
- Collected charge: 10 (4) fC at the start (end)

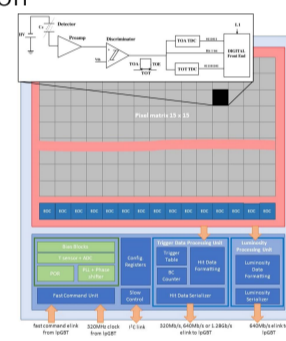
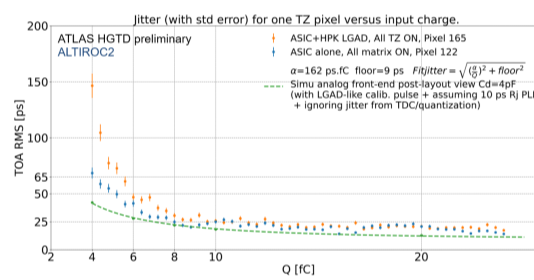


## ALTIROC

- Provides time of arrival (TOA), time over threshold (TOT) and luminosity (number of hits per bunch crossing)
- Small jitter required: 25 ps at 10 fC, <70 ps at 4 fC
- ALTIROC3 bench tests were successful, robustness of the hybridisation needs to be tested

→ **Ongoing:** tests of ALTIROC3 (beam tests in autumn) and design of pre-production chip

→ **Next step:** ALTIROC chip pre-production

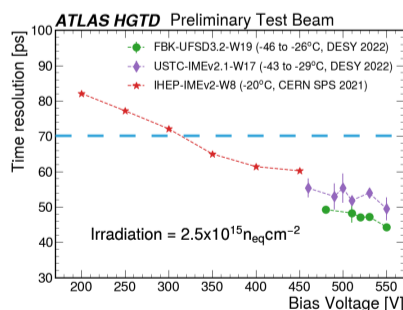
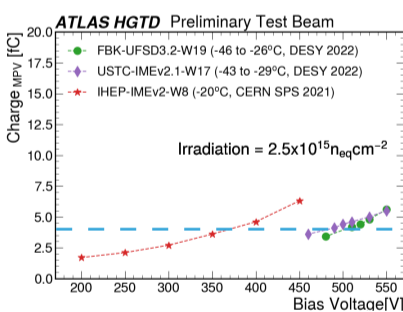


## Sensor results

- End-of-lifetime studies on carbon-enriched LGADs and tests with  $e^-$  (DESY) and  $\pi$  (CERN-SPS) beams on irradiated LGADs
- Good robustness to radiation: operate at  $-30^\circ\text{C}$  to mitigate the impact of radiation
- LGADs prototypes (from different vendors) meet HGTD requirements

→ **Ongoing:** sensor pre-production

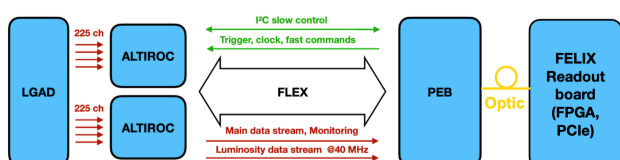
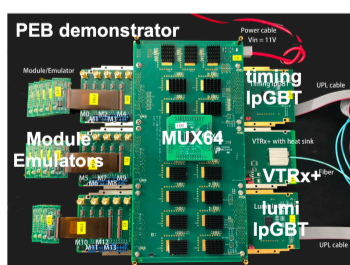
→ **Next step:** test the pre-production to check they still meet the performance targets



## Peripheral Electronics Board

- On detector electronics: lpGBT (Low Power Giga Bit Transceiver), DC-DC converter, VTRX+, multiplexer
- Managing data transmission, power distribution, control and monitoring of the system

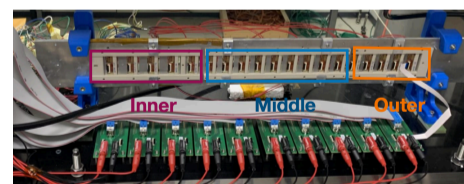
→ **Ongoing:** Work on the characterisation of individual components, prototypes under fabrication



## Demonstrator

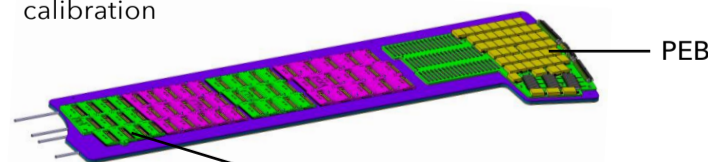
Prototypes used to validate design and integration:

- Heater demonstrator (**done**): study thermal performance with 13 silicon-based heater and validate the module loading procedure



- DAQ demonstrator (**ongoing**): to develop the full chain readout for timing and luminosity data and validate the PEB

- Full demonstrator (**next step**): to validate the full system integration and to test the electronics calibration



54 modules on **detector units** mounted on the cooling plate

